

#### Challenges in Designing 10 GB/S Backplanes

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# Goal



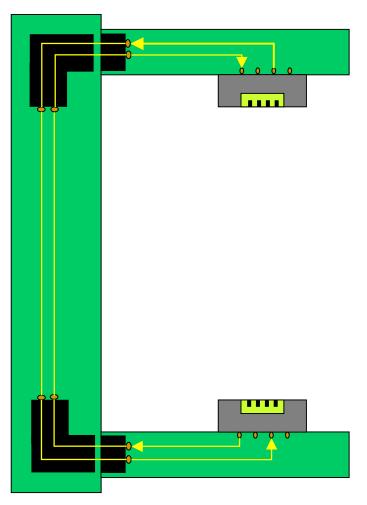
 Share information on design issues in 10 GB/S backplane interconnects

Make recommendations

Provide an implementation perspective

### **Backplane Communication System**





Transmitter
Via
Connector
Via
Long Trace
Via
Connector
Via
Receiver

### **Parameters**

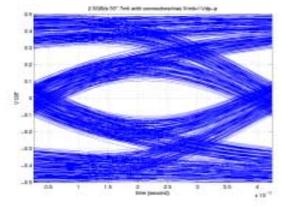


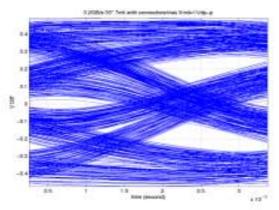
- Total Reflection due to Vias, Connectors, Terminations
- Cross talk
  - Due to vias, Connectors
  - Capacitive and inductive mismatches between differential signals
- High Frequency Loss
  - Differential trace impedance
  - Loss may be a good thing (when alleviating short run reflections)
- EM1
  - Trace configuration will not stop radiation
- Density
  - How close can traces be packed determines cost and aggregate bandwidth

## Problem



- As symbol rates increase,
  - Amplitude decreases, cross talk increases
- Better PCB material solve one problem, create another
- Variations in dispersion cause a myriad of channel conditions
- How to define, identify and compensate for weakest link



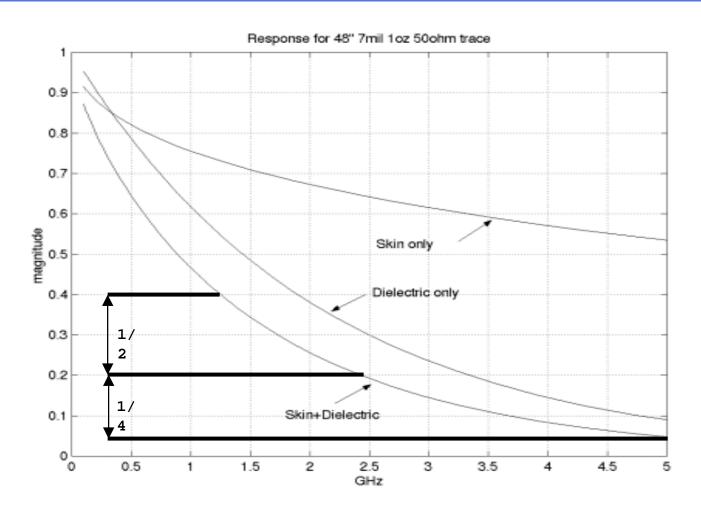


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# From 1.25GB/S to 5GB/S





### **Possible Solutions**



- New strategies for system design offer incremental improvements
  - Utilize new PCB material, connectors
  - Challenge the via culprit
  - Optimize trace structures
- New 2.5G or 3.125G SERDES
  - Offering pre-emphasis, post-emphasis
  - Effectiveness in backplanes remains to be seen
  - SERDES are getting better than ever
- Optical backplanes
  - Flexible, high performance but....
  - Cost issues are limiting deployment

### Recommendation



- View Backplane channel as a communication system
- Exploit the transmission media with targeted solutions
- Robust backplane design requires a targeted solution
- Lower line rate and increase # bits per symbol
  - Reduce number of pins per GB/S
  - Reduce signal integrity problems
  - Increase reach

# A Targeted Solution



#### A targeted backplane transceiver should:

- Optimize for performance & density within any backplane construct
- Work on standard PCB material and connectors
- Adapt to existing serial backplanes
- Alleviate Signal integrity problems: Cross talk, Reflections, Dispersion
- Complement enhancements made to PCB, vias & connectors

## **Problems and Solutions**



Reflection

**Adaptive Equalization** 

Cross Talk

**Adaptive Transmit Levels** 

Dispersion

**Lower Line Frequency** 

• EM1

Scrambler

Density

Higher bit rate per Symbol